

**CLAIMS**

1. An assembly having an axis and comprising:
  - a first support perpendicular to the axis and having a first support perimeter,
  - a first microelectronic module affixed to the first support,
  - a second support perpendicular to the axis and having a second support perimeter;
  - a second microelectronic module affixed to the second support; and
  - a plurality of ribs, each rib being attached to the first support at the first support perimeter outboard the first microelectronic module and to the second support at the second support perimeter outboard the second microelectronic module and extending axially therebetween to maintain said first support and said second support in parallel, spaced relationship.
2. The assembly of claim 1 further comprising a connector strip connected to the first microelectronic module and to the second microelectronic module and extending axially for connecting said first microelectronic module and said second microelectronic module to an external circuit.
3. The assembly of claim 1 wherein the first support perimeter and the second support perimeter are substantially coextensive.
4. The assembly of claim 1 wherein the first support perimeter comprises a first attachment tab, and wherein the second support perimeter comprises a

second attachment tab, and wherein the assembly includes a rib attached to the first attachment tab and the second attachment tab.

5. The assembly of claim 1 wherein the first microelectronic module comprises a flexible substrate and a plurality of electronic components attached to the flexible substrate.

6. The assembly of claim 5 wherein the second microelectronic module comprises a flexible substrate and a plurality of electronic components attached to the flexible substrate.

7. The assembly of claim 1 wherein the first microelectronic module is generally circular and includes a chordal edge, and wherein the assembly further comprises a connector strip connected to the first microelectronic module adjacent said chordal edge.

8. An assembly of claim 1 further comprising  
housing having an inner wall and a housing axis, and  
wherein the microelectronic assembly is coaxially received in the housing,  
said ribs engaging said inner wall and spacing said first and second  
microelectronic modules and said first and second supports spaced apart  
from the inner wall.

9. The assembly of claim 8 wherein the spacing between the inner wall and the first and second microelectronic assemblies is adapted for cooling gas flow.